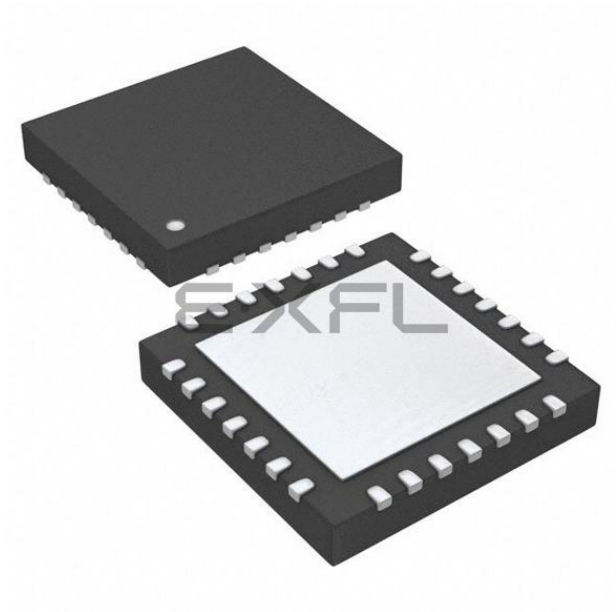

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Applications of "Embedded - Microcontrollers"

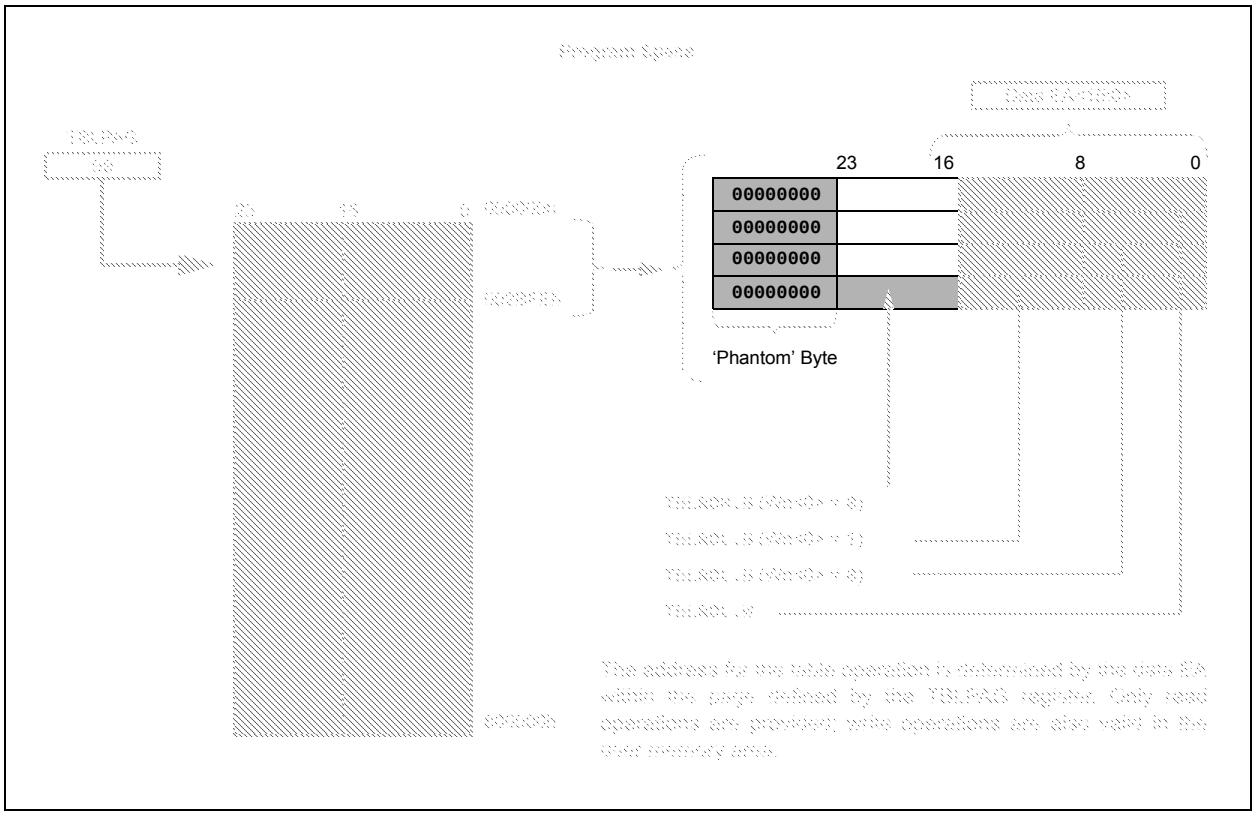
Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	23
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 13x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24fv32ka302-e-ml

In a similar fashion, two table instructions, TBLWTH and TBLWTL, are used to write individual bytes or words to a program space address. The details of their operation are explained in **Section 5.0 "Flash Program Memory"**.

For all table operations, the area of program memory space to be accessed is determined by the Table Memory Page Address register (TBLPAG). TBLPAG covers the entire program memory space of the device, including user and configuration spaces. When TBLPAG<7> = 0, the table page is located in the user memory space. When TBLPAG<7> = 1, the page is located in configuration space.

Note:	Only Table Read operations will execute in the configuration memory space, and only then, in implemented areas, such as the Device ID. Table Write operations are not allowed.

FIGURE 4-6: ACCESSING PROGRAM MEMORY WITH TABLE INSTRUCTIONS



10.2.4.5 Deep Sleep WDT

To enable the DSWDT in Deep Sleep mode, program the Configuration bit, DSWDTEN (FDS<7>). The device Watchdog Timer (WDT) need not be enabled for the DSWDT to function. Entry into Deep Sleep mode automatically resets the DSWDT.

The DSWDT clock source is selected by the DSWDTOSC Configuration bit (FDS<4>). The postscaler options are programmed by the DSWDTPS<3:0> Configuration bits (FDS<3:0>). The minimum time-out period that can be achieved is 2.1 ms and the maximum is 25.7 days. For more details on the FDS Configuration register and DSWDT configuration options, refer to **Section 26.0 "Special Features"**.

10.2.4.6 Switching Clocks in Deep Sleep Mode

Both the RTCC and the DSWDT may run from either SOSC or the LPRC clock source. This allows both the RTCC and DSWDT to run without requiring both the LPRC and SOSC to be enabled together, reducing power consumption.

Running the RTCC from LPRC will result in a loss of accuracy in the RTCC of approximately 5 to 10%. If a more accurate RTCC is required, it must be run from the SOSC clock source. The RTCC clock source is selected with the RTCOSC Configuration bit (FDS<5>).

Under certain circumstances, it is possible for the DSWDT clock source to be off when entering Deep Sleep mode. In this case, the clock source is turned on automatically (if DSWDT is enabled), without the need for software intervention; however, this can cause a delay in the start of the DSWDT counters. In order to avoid this delay when using SOSC as a clock source, the application can activate SOSC prior to entering Deep Sleep mode.

10.2.4.7 Checking and Clearing the Status of Deep Sleep

Upon entry into Deep Sleep mode, the status bit, DPSLP (RCON<10>), becomes set and must be cleared by the software.

On power-up, the software should read this status bit to determine if the Reset was due to an exit from Deep Sleep mode and clear the bit if it is set. Of the four possible combinations of DPSLP and POR bit states, three cases can be considered:

- Both the DPSLP and POR bits are cleared. In this case, the Reset was due to some event other than a Deep Sleep mode exit.
- The DPSLP bit is clear, but the POR bit is set; this is a normal POR.
- Both the DPSLP and POR bits are set. This means that Deep Sleep mode was entered, the device was powered down and Deep Sleep mode was exited.

10.2.4.8 Power-on Resets (PORs)

V_{DD} voltage is monitored to produce PORs. Since exiting from Deep Sleep functionally looks like a POR, the technique described in **Section 10.2.4.7 "Checking and Clearing the Status of Deep Sleep"** should be used to distinguish between Deep Sleep and a true POR event.

When a true POR occurs, the entire device, including all Deep Sleep logic (Deep Sleep registers: RTCC, DSWDT, etc.) is reset.

10.2.4.9 Summary of Deep Sleep Sequence

To review, these are the necessary steps involved in invoking and exiting Deep Sleep mode:

1. The device exits Reset and begins to execute its application code.
2. If DSWDT functionality is required, program the appropriate Configuration bit.
3. Select the appropriate clock(s) for the DSWDT and RTCC (optional).
4. Enable and configure the DSWDT (optional).
5. Enable and configure the RTCC (optional).
6. Write context data to the DSGPRx registers (optional).
7. Enable the INT0 interrupt (optional).
8. Set the DSEN bit in the DSCON register.
9. Enter Deep Sleep by issuing a `PWRSV #SLEEP_MODE` command.
10. The device exits Deep Sleep when a wake-up event occurs.
11. The DSEN bit is automatically cleared.
12. Read and clear the DPSLP status bit in RCON, and the DSWAKE status bits.
13. Read the DSGPRx registers (optional).
14. Once all state related configurations are complete, clear the RELEASE bit.
15. The application resumes normal operation.

REGISTER 10-2: DSWAKE: DEEP SLEEP WAKE-UP SOURCE REGISTER(1)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0, HS
—	—	—	—	—	—	—	DSINT0
bit 15							bit 8

R/W-0, HS	U-0	U-0	R/W-0, HS	R/W-0, HS	R/W-0, HS	U-0	R/W-0, HS
DSFLT	—	—	DSWDT	DSRTCC	DSMCLR	—	DSPOR(2,3)
bit 7							bit 0

Legend:	HS = Hardware Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as '0'

bit 8 **DSINT0:** Deep Sleep Interrupt-on-Change bit
1 = Interrupt-on-change was asserted during Deep Sleep
0 = Interrupt-on-change was not asserted during Deep Sleep

bit 7 **DSFLT:** Deep Sleep Fault Detect bit
1 = A Fault occurred during Deep Sleep and some Deep Sleep configuration settings may have been corrupted
0 = No Fault was detected during Deep Sleep

bit 6-5 **Unimplemented:** Read as '0'

bit 4 **DSWDT:** Deep Sleep Watchdog Timer Time-out bit
1 = The Deep Sleep Watchdog Timer timed out during Deep Sleep
0 = The Deep Sleep Watchdog Timer did not time out during Deep Sleep

bit 3 **DSRTCC:** Deep Sleep Real-Time Clock and Calendar (RTCC) Alarm bit
1 = The Real-Time Clock and Calendar triggered an alarm during Deep Sleep
0 = The Real-Time Clock and Calendar did not trigger an alarm during Deep Sleep

bit 2 **DSMCLR:** Deep Sleep $\overline{\text{MCLR}}$ Event bit
1 = The $\overline{\text{MCLR}}$ pin was active and was asserted during Deep Sleep
0 = The $\overline{\text{MCLR}}$ pin was not active, or was active, but not asserted during Deep Sleep

bit 1 **Unimplemented:** Read as '0'

bit 0 **DSPOR:** Deep Sleep Power-on Reset Event bit(2,3)
1 = The VDD supply POR circuit was active and a POR event was detected
0 = The VDD supply POR circuit was not active, or was active, but did not detect a POR event

Note 1: All register bits are cleared when the DSEN (DSCON<15>) bit is set.

2: All register bits are reset only in the case of a POR event outside of Deep Sleep mode, except bit, DSPOR, which does not reset on a POR event that is caused due to a Deep Sleep exit.

3: Unlike the other bits in this register, this bit can be set outside of Deep Sleep.

11.1.1 OPEN-DRAIN CONFIGURATION

In addition to the PORT, LAT and TRIS registers for data control, each port pin can also be individually configured for either digital or open-drain output. This is controlled by the Open-Drain Control register, ODCx, associated with each port. Setting any of the bits configures the corresponding pin to act as an open-drain output.

The maximum open-drain voltage allowed is the same as the maximum VIH specification.

11.2 Configuring Analog Port Pins

The use of the ANS and TRIS registers control the operation of the A/D port pins. The port pins that are desired as analog inputs must have their corresponding TRISx bit set (input). If the TRISx bit is cleared (output), the digital output level (VOH or VOL) will be converted.

When reading the PORT register, all pins configured as analog input channels will read as cleared (a low level). Analog levels on any pin that is defined as a digital input (including the ANx pins) may cause the input buffer to consume current that exceeds the device specifications.

11.2.1 ANALOG SELECTION REGISTERS

I/O pins with shared analog functionality, such as A/D inputs and comparator inputs, must have their digital inputs shut off when analog functionality is used. Note that analog functionality includes an analog voltage being applied to the pin externally.

To allow for analog control, the ANSx registers are provided. There is one ANS register for each port (ANSA, ANSB and ANSC). Within each ANSx register, there is a bit for each pin that shares analog functionality with the digital I/O functionality.

If a particular pin does not have an analog function, that bit is unimplemented. See Register 11-1 to Register 11-3 for implementation.

REGISTER 11-1: ANSA: ANALOG SELECTION (PORTA)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	—	ANSA<3:0>			
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-4 **Unimplemented:** Read as ‘0’

bit 3-0 **ANSA<3:0>:** Analog Select Control bits

1 = Digital input buffer is not active (use for analog input)

0 = Digital input buffer is active

FIGURE 13-2: TIMER2 AND TIMER4 (16-BIT SYNCHRONOUS) BLOCK DIAGRAM

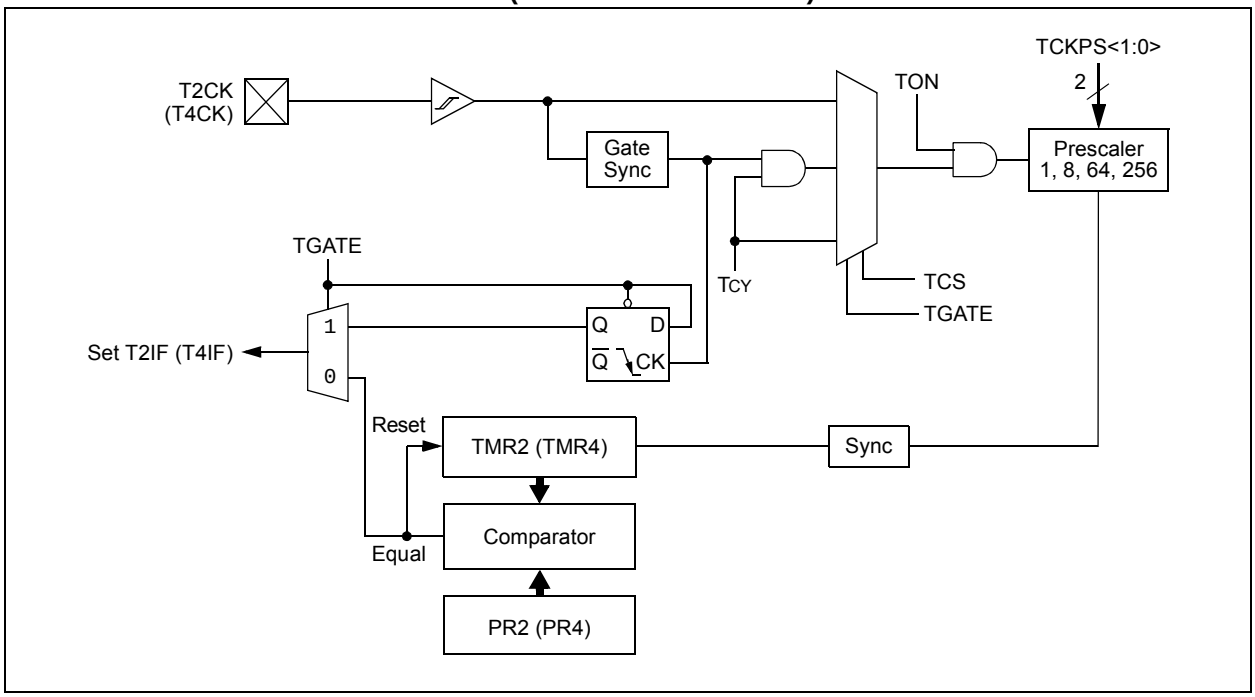
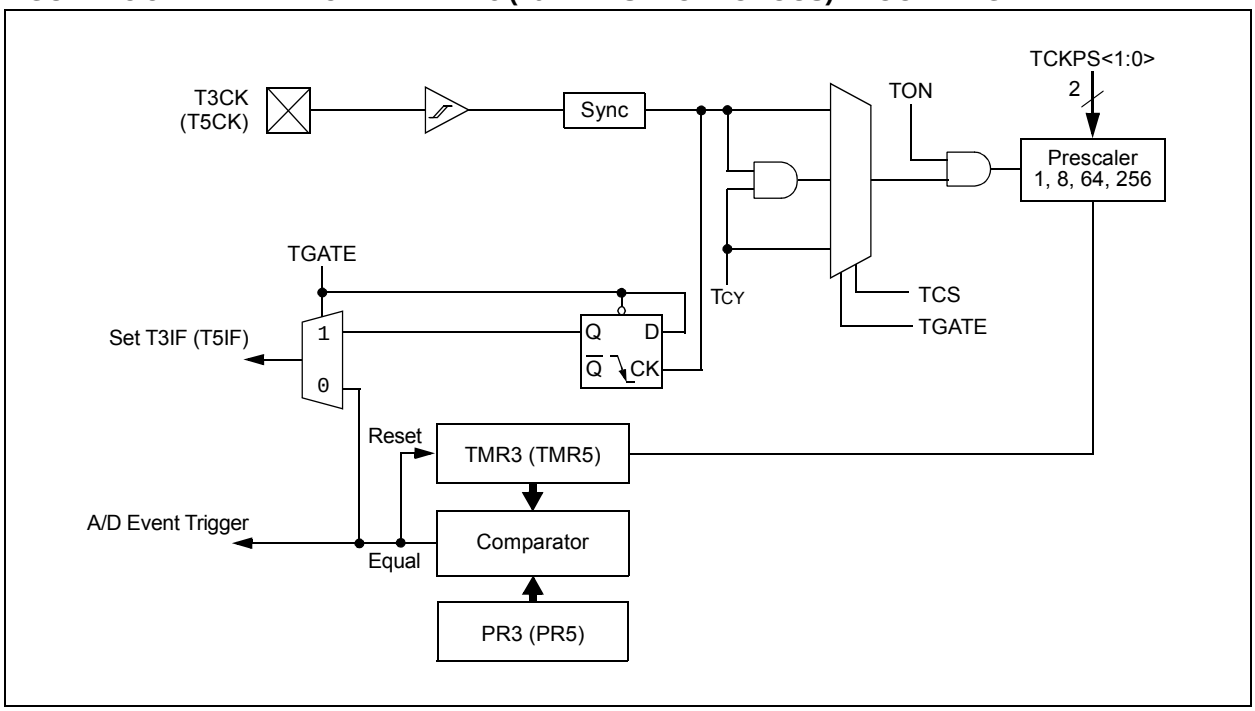


FIGURE 13-3: TIMER3 AND TIMER5 (16-BIT ASYNCHRONOUS) BLOCK DIAGRAM



REGISTER 17-2: I2CxSTAT: I2Cx STATUS REGISTER (CONTINUED)

bit 4 **P:** Stop bit
1 = Indicates that a Stop bit has been detected last
0 = Stop bit was not detected last
Hardware is set or cleared when a Start, Repeated Start or Stop is detected.

bit 3 **S:** Start bit
1 = Indicates that a Start (or Repeated Start) bit has been detected last
0 = Start bit was not detected last
Hardware is set or clear when a Start, Repeated Start or Stop is detected.

bit 2 **R/$\overline{W}$:** Read/$\overline{\text{Write}}$ Information bit (when operating as I^2C slave)
1 = Read – indicates data transfer is output from the slave
0 = Write – indicates data transfer is input to the slave
Hardware is set or clear after the reception of an I^2C device address byte.

bit 1 **RBF:** Receive Buffer Full Status bit
1 = Receive is complete, I2CxRCV is full
0 = Receive is not complete, I2CxRCV is empty
Hardware is set when I2CxRCV is written with a received byte; hardware is clear when the software reads I2CxRCV.

bit 0 **TBF:** Transmit Buffer Full Status bit
1 = Transmit is in progress, I2CxTRN is full
0 = Transmit is complete, I2CxTRN is empty
Hardware is set when the software writes to I2CxTRN; hardware is clear at the completion of data transmission.

REGISTER 18-2: UxSTA: UARTx STATUS AND CONTROL REGISTER

R/W-0	R/W-0	R/W-0	U-0	R/W-0, HC	R/W-0	R-0, HSC	R-1, HSC
UTXISEL1	UTXINV	UTXISEL0	—	UTXBRK	UTXEN	UTXBF	TRMT
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R-1, HSC	R-0, HSC	R-0, HSC	R/C-0, HS	R-0, HSC
URXISEL1	URXISEL0	ADDEN	RIDLE	PERR	FERR	OERR	URXDA
bit 7							bit 0

Legend:			
HS = Hardware Settable bit	C = Clearable bit	HSC = Hardware Settable/Clearable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	HC = Hardware Clearable bit

bit 15,13 **UTXISEL<1:0>:** UARTx Transmission Interrupt Mode Selection bits
- 11 = Reserved; do not use
- 10 = Interrupt when a character is transferred to the Transmit Shift Register (TSR) and as a result, the transmit buffer becomes empty
- 01 = Interrupt when the last character is shifted out of the Transmit Shift Register; all transmit operations are completed
- 00 = Interrupt when a character is transferred to the Transmit Shift Register (this implies there is at least one character open in the transmit buffer)

bit 14 **UTXINV:** IrDA® Encoder Transmit Polarity Inversion bit

If IREN = 0:
- 1 = UxTX Idle '0'
- 0 = UxTX Idle '1'

If IREN = 1:
- 1 = UxTX Idle '1'
- 0 = UxTX Idle '0'

bit 12 **Unimplemented:** Read as '0'

bit 11 **UTXBRK:** UARTx Transmit Break bit
- 1 = Sends Sync Break on next transmission – Start bit, followed by twelve '0' bits, followed by Stop bit; cleared by hardware upon completion
- 0 = Sync Break transmission is disabled or completed

bit 10 **UTXEN:** UARTx Transmit Enable bit
- 1 = Transmit is enabled; UxTX pin is controlled by UARTx
- 0 = Transmit is disabled; any pending transmission is aborted and the buffer is reset. UxTX pin is controlled by the PORT register.

bit 9 **UTXBF:** UARTx Transmit Buffer Full Status bit (read-only)
- 1 = Transmit buffer is full
- 0 = Transmit buffer is not full, at least one more character can be written

bit 8 **TRMT:** Transmit Shift Register Empty bit (read-only)
- 1 = Transmit Shift Register is empty and the transmit buffer is empty (the last transmission has completed)
- 0 = Transmit Shift Register is not empty; a transmission is in progress or queued

bit 7-6 **URXISEL<1:0>:** UARTx Receive Interrupt Mode Selection bits
- 11 = Interrupt is set on a RSR transfer, making the receive buffer full (i.e., has 4 data characters)
- 10 = Interrupt is set on a RSR transfer, making the receive buffer 3/4 full (i.e., has 3 data characters)
- 0x = Interrupt is set when any character is received and transferred from the RSR to the receive buffer; receive buffer has one or more characters.

19.0 REAL-TIME CLOCK AND CALENDAR (RTCC)

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the Real-Time Clock and Calendar, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"RTCC with External Power Control"** (DS39745).

The RTCC provides the user with a Real-Time Clock and Calendar (RTCC) function that can be calibrated.

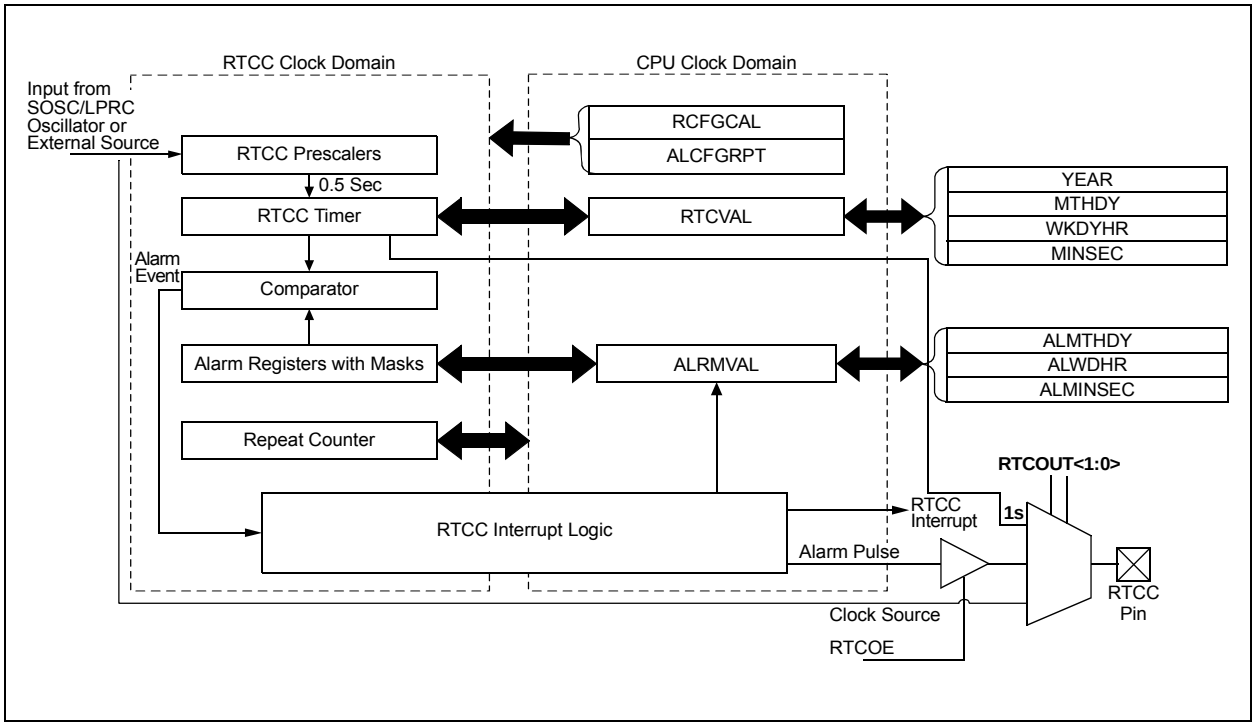
Key features of the RTCC module are:

- Operates in Deep Sleep mode
- Selectable clock source
- Provides hours, minutes and seconds using 24-hour format
- Visibility of one half second period
- Provides calendar – weekday, date, month and year
- Alarm-configurable for half a second, one second, 10 seconds, one minute, 10 minutes, one hour, one day, one week, one month or one year
- Alarm repeat with decrementing counter
- Alarm with indefinite repeat chime
- Year 2000 to 2099 leap year correction
- BCD format for smaller software overhead
- Optimized for long-term battery operation
- User calibration of the 32.768 kHz clock crystal/32K INTRC frequency with periodic auto-adjust
- Optimized for long-term battery operation
- Fractional second synchronization
- Calibration to within ±2.64 seconds error per month
- Calibrates up to 260 ppm of crystal error
- Ability to periodically wake-up external devices without CPU intervention (external power control)
- Power control output for external circuit control
- Calibration takes effect every 15 seconds
- Runs from any one of the following:
  - External Real-Time Clock of 32.768 kHz
  - Internal 31.25 kHz LPRC Clock
  - 50 Hz or 60 Hz External Input

19.1 RTCC Source Clock

The user can select between the SOSC crystal oscillator, LPRC internal oscillator or an external 50 Hz/60 Hz power line input as the clock reference for the RTCC module. This gives the user an option to trade off system cost, accuracy and power consumption, based on the overall system needs.

FIGURE 19-1: RTCC BLOCK DIAGRAM



19.2.6 ALRMVAL REGISTER MAPPINGS

REGISTER 19-8: ALMTHDY: ALARM MONTH AND DAY VALUE REGISTER(1)

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	MTHTEN0	MTHONE3	MTHONE2	MTHONE1	MTHONE0
bit 15							bit 8

U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	DAYTEN1	DAYTEN0	DAYONE3	DAYONE2	DAYONE1	DAYONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12 **MTHTEN0:** Binary Coded Decimal Value of Month's Tens Digit bit
Contains a value of '0' or '1'.

bit 11-8 **MTHONE<3:0>:** Binary Coded Decimal Value of Month's Ones Digit bits
Contains a value from 0 to 9.

bit 7-6 **Unimplemented:** Read as '0'

bit 5-4 **DAYTEN<1:0>:** Binary Coded Decimal Value of Day's Tens Digit bits
Contains a value from 0 to 3.

bit 3-0 **DAYONE<3:0>:** Binary Coded Decimal Value of Day's Ones Digit bits
Contains a value from 0 to 9.

Note 1: A write to this register is only allowed when RTCWREN = 1.

REGISTER 19-9: ALWDHR: ALARM WEEKDAY AND HOURS VALUE REGISTER(1)

U-0	U-0	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x
—	—	—	—	—	WDAY2	WDAY1	WDAY0
bit 15							bit 8

U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	HRTEN1	HRTEN0	HRONE3	HRONE2	HRONE1	HRONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-11 **Unimplemented:** Read as '0'

bit 10-8 **WDAY<2:0>:** Binary Coded Decimal Value of Weekday Digit bits
Contains a value from 0 to 6.

bit 7-6 **Unimplemented:** Read as '0'

bit 5-4 **HRTEN<1:0>:** Binary Coded Decimal Value of Hour's Tens Digit bits
Contains a value from 0 to 2.

bit 3-0 **HRONE<3:0>:** Binary Coded Decimal Value of Hour's Ones Digit bits
Contains a value from 0 to 9.

Note 1: A write to this register is only allowed when RTCWREN = 1.

REGISTER 20-3: CRCXORL: CRC XOR POLYNOMIAL REGISTER, LOW BYTE

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
X<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0
X<7:1>							—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-1 **X<15:1>:** XOR of Polynomial Term X^n Enable bits

bit 0 **Unimplemented:** Read as '0'

REGISTER 20-4: CRCXORH: CRC XOR POLYNOMIAL REGISTER, HIGH BYTE

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
X<31:24>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
X<23:16>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **X<31:16>:** XOR of Polynomial Term X^n Enable bits

25.0 CHARGE TIME MEASUREMENT UNIT (CTMU)

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the Charge Measurement Unit, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Charge Time Measurement Unit (CTMU) and CTMU Operation with Threshold Detect"** (DS30009743).

The Charge Time Measurement Unit (CTMU) is a flexible analog module that provides charge measurement, accurate differential time measurement between pulse sources and asynchronous pulse generation. Its key features include:

- Thirteen external edge input trigger sources
- Polarity control for each edge source
- Control of edge sequence
- Control of response to edge levels or edge transitions
- Time measurement resolution of one nanosecond
- Accurate current source suitable for capacitive measurement

Together with other on-chip analog modules, the CTMU can be used to precisely measure time, measure capacitance, measure relative changes in capacitance or generate output pulses that are independent of the system clock. The CTMU module is ideal for interfacing with capacitive-based touch sensors.

The CTMU is controlled through three registers: CTMUCON1, CTMUCON2 and CTMUICON. CTMUCON1 enables the module and controls the mode of operation of the CTMU, as well as controlling edge sequencing. CTMUCON2 controls edge source selection and edge source polarity selection. The CTMUICON register selects the current range of current source and trims the current.

25.1 Measuring Capacitance

The CTMU module measures capacitance by generating an output pulse, with a width equal to the time between edge events, on two separate input channels. The pulse edge events to both input channels can be selected from several internal peripheral modules (OC1, Timer1, any input capture or comparator module) and up to 13 external pins (CTED1 through CTED13). This pulse is used with the module's precision current source to calculate capacitance according to the relationship:

EQUATION 25-1:

$$I = C \cdot \frac{dV}{dT}$$

For capacitance measurements, the A/D Converter samples an external capacitor (CAPP) on one of its input channels after the CTMU output's pulse. A Precision Resistor (RPR) provides current source calibration on a second A/D channel. After the pulse ends, the converter determines the voltage on the capacitor. The actual calculation of capacitance is performed in software by the application.

Figure 25-1 illustrates the external connections used for capacitance measurements, and how the CTMU and A/D modules are related in this application. This example also shows the edge events coming from Timer1, but other configurations using external edge sources are possible. A detailed discussion on measuring capacitance and time with the CTMU module is provided in the *"dsPIC33/PIC24 Family Reference Manual"*.

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Assembly Mnemonic	Assembly Syntax		Description	# of Words	# of Cycles	Status Flags Affected
BTSS	BTSS	f,#bit4	Bit Test f, Skip if Set	1	1 (2 or 3)	None
	BTSS	Ws,#bit4	Bit Test Ws, Skip if Set	1	1 (2 or 3)	None
BTST	BTST	f,#bit4	Bit Test f	1	1	Z
	BTST.C	Ws,#bit4	Bit Test Ws to C	1	1	C
	BTST.Z	Ws,#bit4	Bit Test Ws to Z	1	1	Z
	BTST.C	Ws,Wb	Bit Test Ws<Wb> to C	1	1	C
	BTST.Z	Ws,Wb	Bit Test Ws<Wb> to Z	1	1	Z
BTSTS	BTSTS	f,#bit4	Bit Test then Set f	1	1	Z
	BTSTS.C	Ws,#bit4	Bit Test Ws to C, then Set	1	1	C
	BTSTS.Z	Ws,#bit4	Bit Test Ws to Z, then Set	1	1	Z
CALL	CALL	lit23	Call Subroutine	2	2	None
	CALL	Wn	Call Indirect Subroutine	1	2	None
CLR	CLR	f	f = 0x0000	1	1	None
	CLR	WREG	WREG = 0x0000	1	1	None
	CLR	Ws	Ws = 0x0000	1	1	None
CLRWDT	CLRWDT		Clear Watchdog Timer	1	1	WDTO, Sleep
COM	COM	f	$f = \overline{f}$	1	1	N, Z
	COM	f,WREG	$WREG = \overline{f}$	1	1	N, Z
	COM	Ws,Wd	$Wd = \overline{Ws}$	1	1	N, Z
CP	CP	f	Compare f with WREG	1	1	C, DC, N, OV, Z
	CP	Wb,#lit5	Compare Wb with lit5	1	1	C, DC, N, OV, Z
	CP	Wb,Ws	Compare Wb with Ws (Wb – Ws)	1	1	C, DC, N, OV, Z
CP0	CP0	f	Compare f with 0x0000	1	1	C, DC, N, OV, Z
	CP0	Ws	Compare Ws with 0x0000	1	1	C, DC, N, OV, Z
CPB	CPB	f	Compare f with WREG, with Borrow	1	1	C, DC, N, OV, Z
	CPB	Wb,#lit5	Compare Wb with lit5, with Borrow	1	1	C, DC, N, OV, Z
	CPB	Wb,Ws	Compare Wb with Ws, with Borrow ($Wb – Ws – \overline{C}$)	1	1	C, DC, N, OV, Z
CPSEQ	CPSEQ	Wb,Wn	Compare Wb with Wn, Skip if =	1	1 (2 or 3)	None
CPSGT	CPSGT	Wb,Wn	Compare Wb with Wn, Skip if >	1	1 (2 or 3)	None
CPSLT	CPSLT	Wb,Wn	Compare Wb with Wn, Skip if <	1	1 (2 or 3)	None
CPSNE	CPSNE	Wb,Wn	Compare Wb with Wn, Skip if ≠	1	1 (2 or 3)	None
DAW	DAW	Wn	Wn = Decimal Adjust Wn	1	1	C
DEC	DEC	f	f = f –1	1	1	C, DC, N, OV, Z
	DEC	f,WREG	WREG = f –1	1	1	C, DC, N, OV, Z
	DEC	Ws,Wd	Wd = Ws – 1	1	1	C, DC, N, OV, Z
DEC2	DEC2	f	f = f – 2	1	1	C, DC, N, OV, Z
	DEC2	f,WREG	WREG = f – 2	1	1	C, DC, N, OV, Z
	DEC2	Ws,Wd	Wd = Ws – 2	1	1	C, DC, N, OV, Z
DISI	DISI	#lit14	Disable Interrupts for k Instruction Cycles	1	1	None
DIV	DIV.SW	Wm,Wn	Signed 16/16-bit Integer Divide	1	18	N, Z, C, OV
	DIV.SD	Wm,Wn	Signed 32/16-bit Integer Divide	1	18	N, Z, C, OV
	DIV.UW	Wm,Wn	Unsigned 16/16-bit Integer Divide	1	18	N, Z, C, OV
	DIV.UD	Wm,Wn	Unsigned 32/16-bit Integer Divide	1	18	N, Z, C, OV
EXCH	EXCH	Wns,Wnd	Swap Wns with Wnd	1	1	None
FF1L	FF1L	Ws,Wnd	Find First One from Left (MSb) Side	1	1	C
FF1R	FF1R	Ws,Wnd	Find First One from Right (LSb) Side	1	1	C

TABLE 29-4: HIGH/LOW–VOLTAGE DETECT CHARACTERISTICS

Standard Operating Conditions: 1.8V to 3.6V PIC24F32KA3XX **2.0V to 5.5V PIC24FV32KA3XX** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended								
Param No.	**Symbol**	**Characteristic**		**Min**	**Typ**	**Max**	**Units**	**Conditions**
DC18	VHLVD	HLVD Voltage on VDD Transition	HLVDL<3:0> = 0000(2)	—	—	1.90	V	
			HLVDL<3:0> = 0001	1.86	—	2.13	V	
			HLVDL<3:0> = 0010	2.08	—	2.35	V	
			HLVDL<3:0> = 0011	2.22	—	2.53	V	
			HLVDL<3:0> = 0100	2.30	—	2.62	V	
			HLVDL<3:0> = 0101	2.49	—	2.84	V	
			HLVDL<3:0> = 0110	2.73	—	3.10	V	
			HLVDL<3:0> = 0111	2.86	—	3.25	V	
			HLVDL<3:0> = 1000	3.00	—	3.41	V	
			HLVDL<3:0> = 1001	3.16	—	3.59(1)	V	
			HLVDL<3:0> = 1010(1)	3.33	—	3.79	V	
			HLVDL<3:0> = 1011(1)	3.53	—	4.01	V	
			HLVDL<3:0> = 1100(1)	3.74	—	4.26	V	
			HLVDL<3:0> = 1101(1)	4.00	—	4.55	V	
			HLVDL<3:0> = 1110(1)	4.28	—	4.87	V	

Note 1: These trip points should not be used on PIC24FXXKA30X devices.

2: This trip point should not be used on PIC24FVXXKA30X devices.

TABLE 29-5: BOR TRIP POINTS

Standard Operating Conditions: 1.8V to 3.6V PIC24F32KA3XX **2.0V to 5.5V PIC24FV32KA3XX** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended								
Param No.	**Sym**	**Characteristic**		**Min**	**Typ**	**Max**	**Units**	**Conditions**
DC15		BOR Hysteresis		—	5	—	mV	
DC19		BOR Voltage on VDD Transition	BORV<1:0> = 00	—	—	—	—	Valid for LPBOR and DSBOR (**Note 1)**
			BORV<1:0> = 01	2.90	3	3.38	V	
			BORV<1:0> = 10	2.53	2.7	3.07	V	
			BORV<1:0> = 11	1.75	1.85	2.05	V	**(Note 2)**
			BORV<1:0> = 11	1.95	2.05	2.16	V	**(Note 3)**

Note 1: LPBOR re-arms the POR circuit but does not cause a BOR.

2: This is valid for PIC24F (3.3V) devices.

3: This is valid for PIC24FV (5V) devices.

FIGURE 29-16: UARTx BAUD RATE GENERATOR OUTPUT TIMING

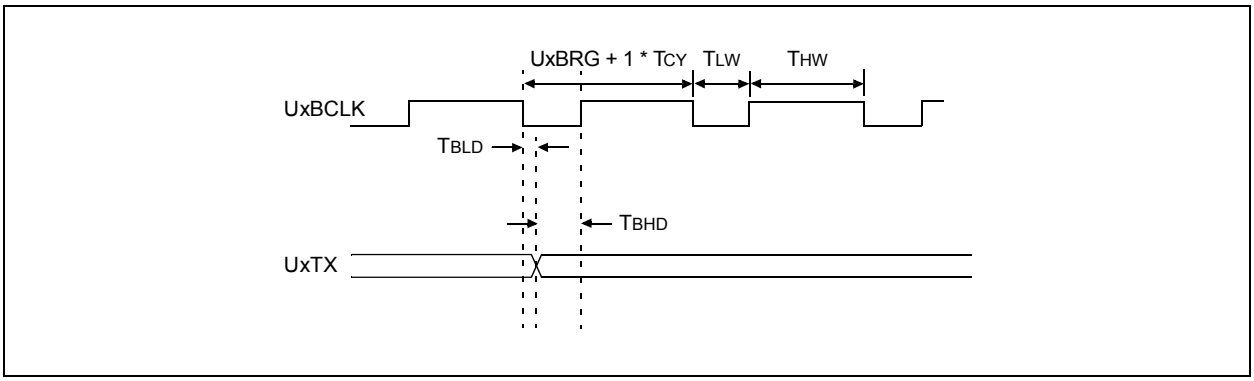


FIGURE 29-17: UARTx START BIT EDGE DETECTION

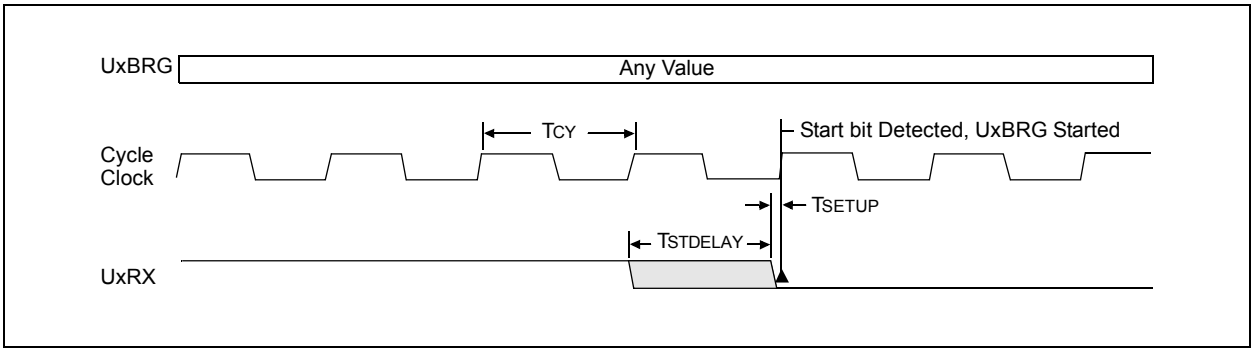


TABLE 29-35: UARTx TIMING REQUIREMENTS

AC CHARACTERISTICS		Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C (Industrial) -40°C ≤ TA ≤ +125°C (Extended)			
Symbol	**Characteristics**	**Min**	**Typ**	**Max**	**Units**
TLW	UxBCLK High Time	20	TCY/2	—	ns
THW	UxBCLK Low Time	20	(TCY * UxBRG) + TCY/2	—	ns
TBLD	UxBCLK Falling Edge Delay from UxTX	-50	—	50	ns
TBHD	UxBCLK Rising Edge Delay from UxTX	TCY/2 – 50	—	TCY/2 + 50	ns
TWAK	Minimum Low on UxRX Line to Cause Wake-up	—	1	—	µs
TCTS	Minimum Low on $\overline{\text{UxCTS}}$ Line to Start Transmission	Tcy	—	—	ns
TSETUP	Start bit Falling Edge to System Clock Rising Edge Setup Time	3	—	—	ns
TSTDELAY	Maximum Delay in the Detection of the Start bit Falling Edge	—	—	TCY + TSETUP	ns

FIGURE 30-5: TYPICAL IDD vs. VDD (8 MHz, EC MODE)

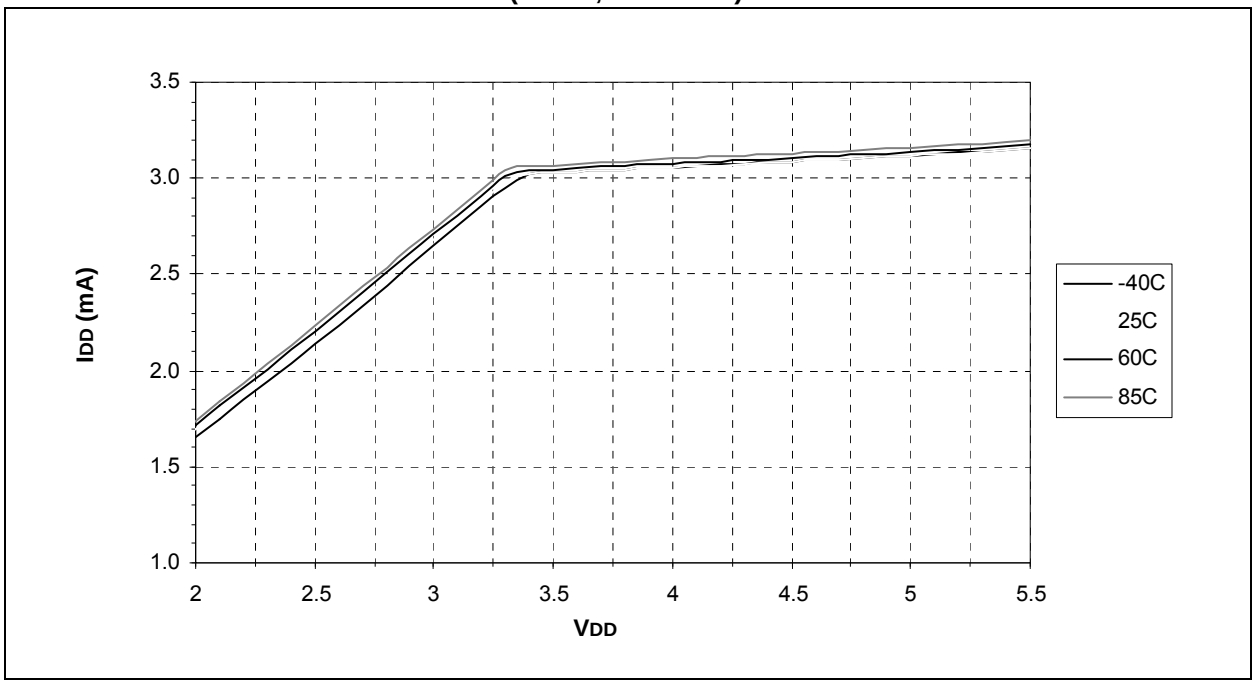


FIGURE 30-6: TYPICAL IDD vs. VDD (FRC MODE)

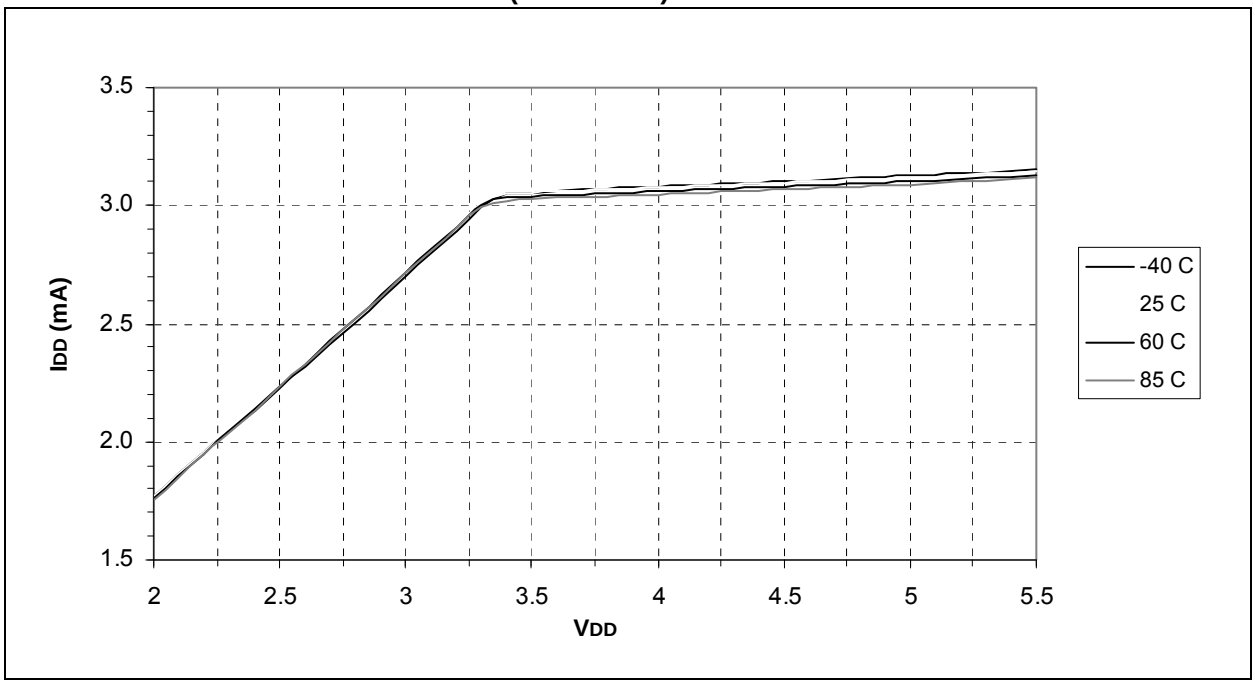


FIGURE 30-33: TYPICAL BAND GAP VOLTAGE vs. TEMPERATURE (2.0V ≤ VDD ≤ 5.5V)

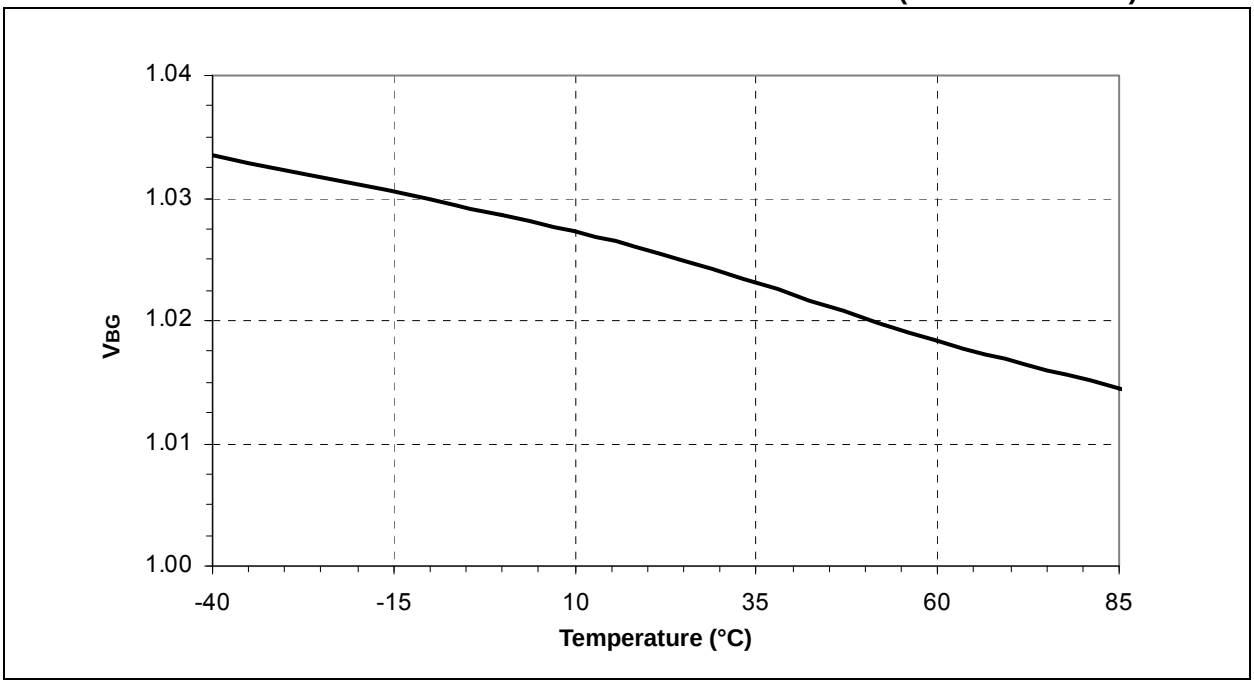


FIGURE 30-34: TYPICAL VOLTAGE REGULATOR OUTPUT vs. VDD

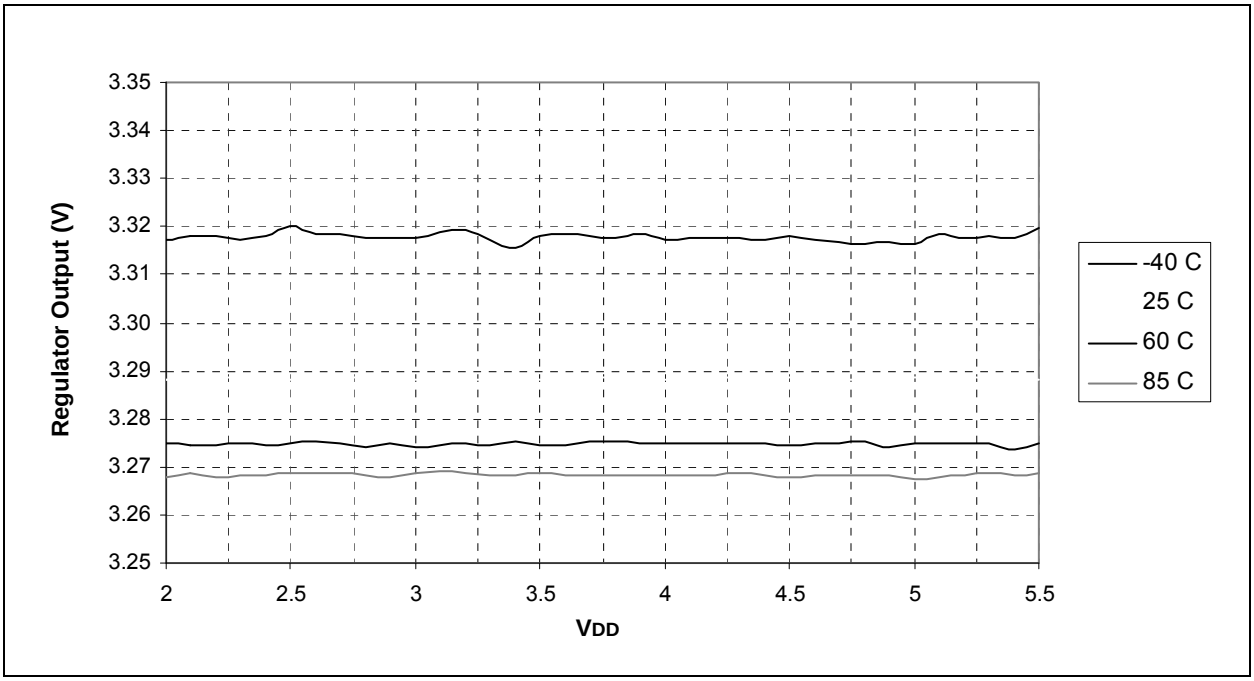


FIGURE 30-46: TYPICAL ΔIWDT VS. VDD

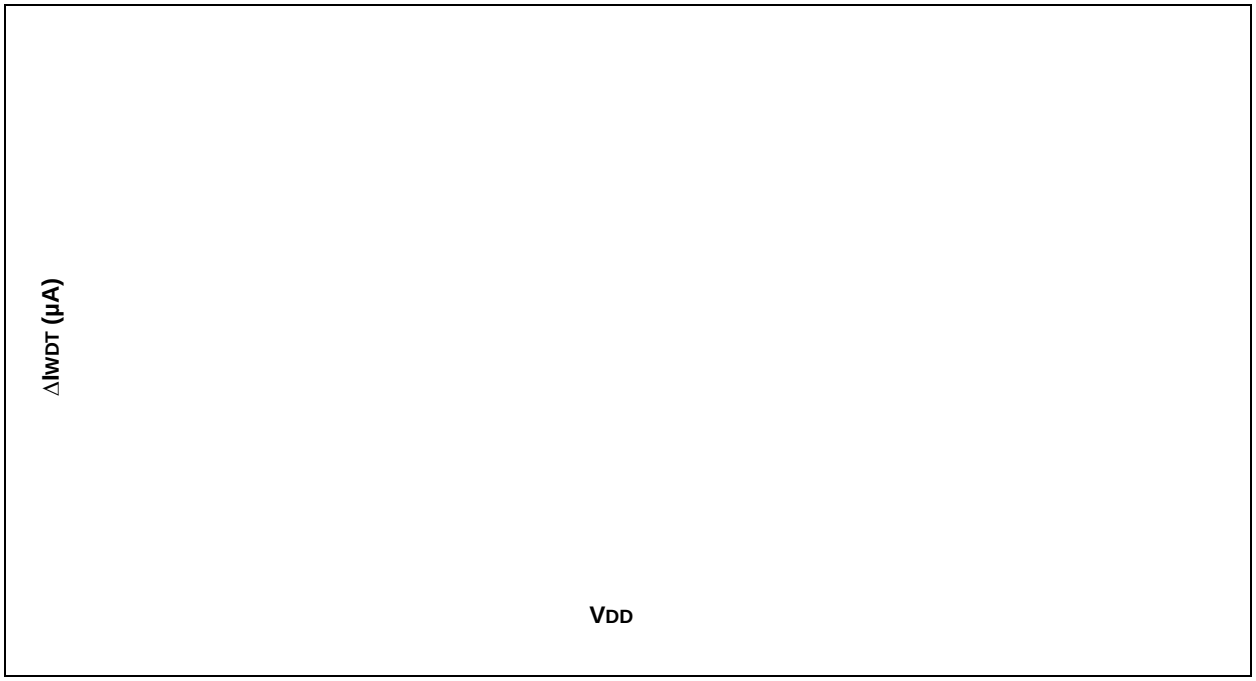
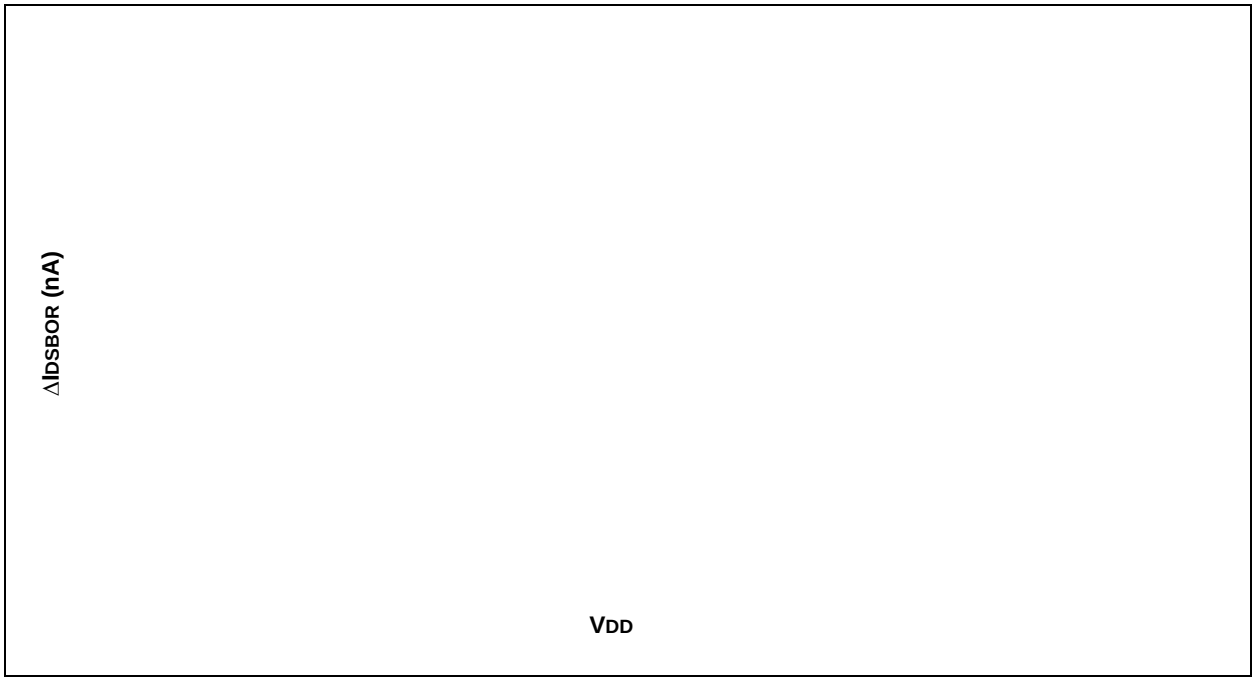
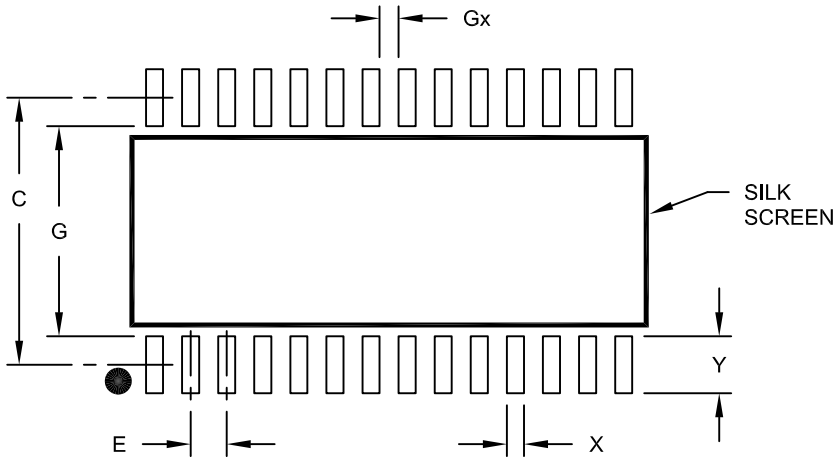


FIGURE 30-47: TYPICAL ΔIDSBOR VS. VDD



28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		9.40	
Contact Pad Width (X28)	X			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

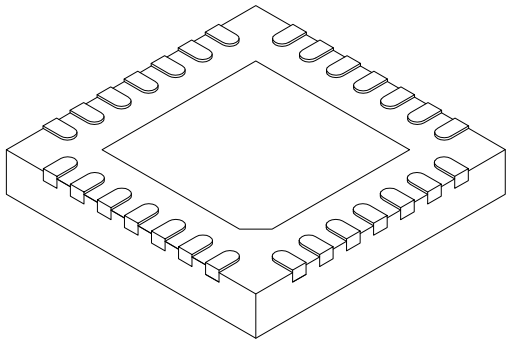
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A

28-Lead Plastic Quad Flat, No Lead Package (ML) - 6x6 mm Body [QFN] With 0.55 mm Terminal Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.20 REF	
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	3.65	3.70	4.20
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	3.65	3.70	4.20
Terminal Width	b	0.23	0.30	0.35
Terminal Length	L	0.50	0.55	0.70
Terminal-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-105C Sheet 2 of 2

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